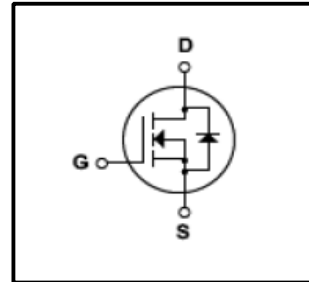


Silicon N-Channel MOSFET

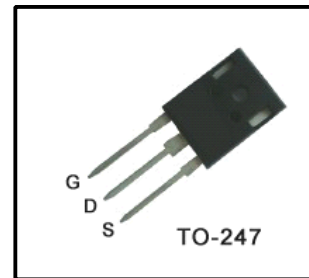
Features

- 24A,500V, $R_{DS(on)}$ (Max0.19 Ω)@ $V_{GS}=10V$
- Ultra-low Gate charge(Typical 90nC)
- Fast Switching Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150 $^{\circ}C$)



General Description

This N-Channel enhancement mode power field effect transistors are produced using Winsemi's proprietary, planar stripe ,DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance , provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.



Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|----------------|---|----------|----------------|
| V_{DSS} | Drain Source Voltage | 500 | V |
| I_D | Continuous Drain Current(@ $T_c=25^{\circ}C$) | 24 | A |
| | Continuous Drain Current(@ $T_c=100^{\circ}C$) | 15.2 | A |
| I_{DM} | Drain Current Pulsed (Note1) | 96 | A |
| V_{GS} | Gate to Source Voltage | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note2) | 1100 | mJ |
| E_{AR} | Repetitive Avalanche Energy (Note1) | 29 | mJ |
| dv/dt | Peak Diode Recovery dv /dt (Note3) | 4.5 | V/ ns |
| P_D | Total Power Dissipation(@ $T_c=25^{\circ}C$) | 290 | W |
| | Derating Factor above 25 $^{\circ}C$ | 2.33 | W/ $^{\circ}C$ |
| T_J, T_{stg} | Junction and Storage Temperature | -55~150 | $^{\circ}C$ |
| T_L | Channel Temperature | 300 | $^{\circ}C$ |

Thermal Characteristics

| Symbol | Parameter | Value | | | Units |
|-----------|---|-------|------|------|---------------|
| | | Min | Typ | Max | |
| R_{QJC} | Thermal Resistance , Junction -to -Case | - | - | 0.43 | $^{\circ}C/W$ |
| R_{QCS} | Thermal Resistance , Case-to-Sink | - | 0.24 | - | $^{\circ}C/W$ |
| R_{QJA} | Thermal Resistance , Junction-to -Ambient | - | - | 40 | $^{\circ}C/W$ |

Electrical Characteristics(Tc=25°C)

| Characteristics | Symbol | Test Condition | Min | Type | Max | Unit | |
|--|------------------------------|--|--|------|-----------|---------------|----|
| Gate leakage current | I_{GSS} | $V_{GS}=\pm 25V, V_{DS}=0V$ | - | - | ± 100 | nA | |
| Gate-source breakdown voltage | $V_{(BR)GSS}$ | $I_G=\pm 10 \mu A, V_{DS}=0V$ | ± 30 | - | - | V | |
| Drain cut -off current | I_{DSS} | $V_{DS}=500V, V_{GS}=0V$ | - | - | 1 | μA | |
| | | $V_{DS}=400V, T_c=125^\circ C$ | | | 10 | | |
| Drain -source breakdown voltage | $V_{(BR)DSS}$ | $I_D=10 mA, V_{GS}=0V$ | 500 | - | - | V | |
| Breakdown voltage Temperature coefficient | $\Delta BV_{DSS}/\Delta T_J$ | $I_D=250\mu A, \text{Referenced to } 25^\circ C$ | - | 0.53 | - | V/ $^\circ C$ | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=10V, I_D=1mA$ | 3.0 | - | 5.0 | V | |
| Drain -source ON resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=9A$ | - | 0.16 | 0.19 | Ω | |
| Forward Transconductance | gfs | $V_{DS}=40V, I_D=9A$ | - | 22 | - | S | |
| Input capacitance | C_{iss} | $V_{DS}=25V,$ | - | 3500 | 4500 | pF | |
| Reverse transfer capacitance | C_{rss} | $V_{GS}=0V,$ | - | 55 | 70 | | |
| Output capacitance | C_{oss} | $f=1MHz$ | - | 520 | 670 | | |
| Switching time | Rise time | tr | $V_{DD}=250V,$ $I_D=18A$ $R_G=25\Omega$ (Note4,5) | - | 250 | 500 | ns |
| | Turn-on time | ton | | - | 80 | 170 | |
| | Fall time | tf | | - | 155 | 320 | |
| | Turn-off time | toff | | - | 200 | 400 | |
| Total gate charge(gate-source plus gate-drain) | Qg | $V_{DD}=400V,$ $V_{GS}=10V,$ | - | 90 | 120 | nC | |
| Gate-source charge | Qgs | $I_D=18A$ | - | 23 | - | | |
| Gate-drain("miller") Charge | Qgd | (Note4,5) | - | 44 | - | | |

Source-Drain Ratings and Characteristics(Ta=25°C)

| Characteristics | Symbol | Test Condition | Min | Type | Max | Unit |
|----------------------------------|-----------|--------------------------------|-----|------|-----|---------|
| Continuous drain reverse current | I_{DR} | - | - | - | 24 | A |
| Pulse drain reverse current | I_{DRP} | - | - | - | 96 | A |
| Forward voltage(diode) | V_{DSF} | $I_{DR}=24A, V_{GS}=0V$ | - | - | 1.4 | V |
| Reverse recovery time | trr | $I_{DR}=24A, V_{GS}=0V,$ | - | 400 | - | ns |
| Reverse recovery charge | Qrr | $dI_{DR} / dt = 100 A / \mu s$ | - | 4.3 | - | μC |

Note 1.Repeativity rating :pulse width limited by junction temperature

2.L=3.4mH $I_{AS}=24A, V_{DD}=50V, R_G=25\Omega, \text{Starting } T_J=25^\circ C$

3. $I_{SD}\leq 24A, di/dt\leq 200A/\mu s, V_{DD}<BV_{DSS}, \text{STARTING } T_J=25^\circ C$

4. Pulse Test:Pulse Width $\leq 300\mu s, \text{Duty Cycles}\leq 2\%$

5. Essentially independent of operating temperature.

This transistor is an electrostatic sensitive device

Please handle with caution

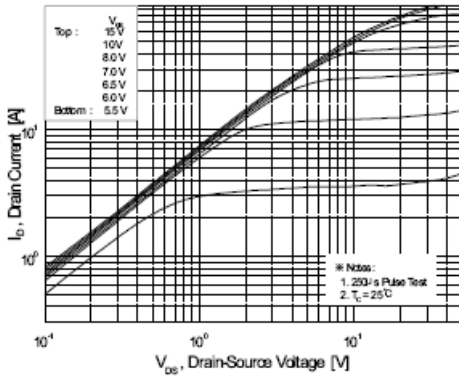


Fig.1 On State Characteristics

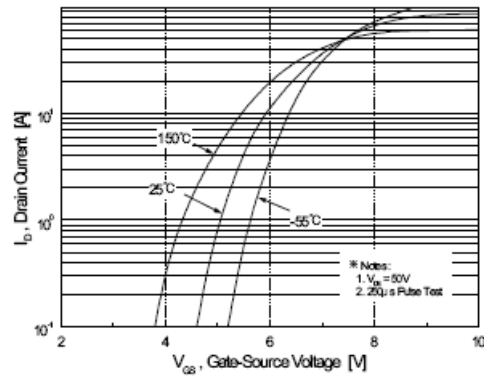


Fig.2 Transfer Current Characteristics

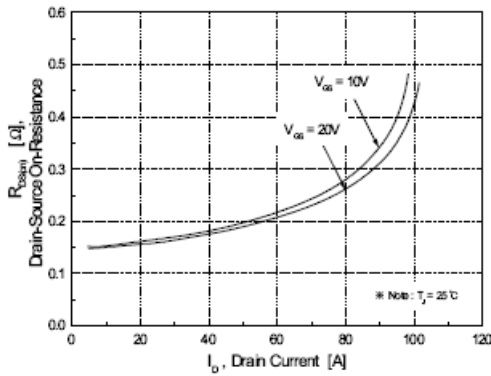


Fig.3 On-Resistance Variation vs Drain Current and gate voltage

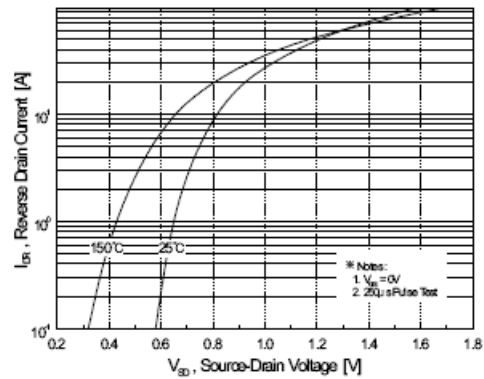


Fig.4 Body Diode Forward Voltage Variation with Source Current and Temperature

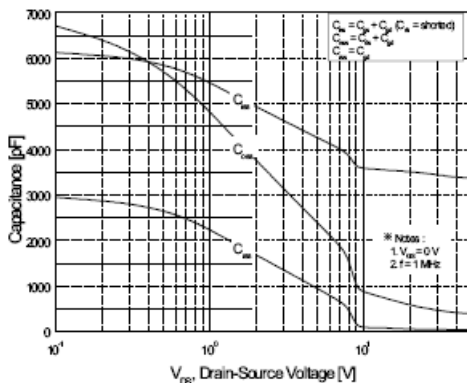


Fig.5 Capacitance Characteristics

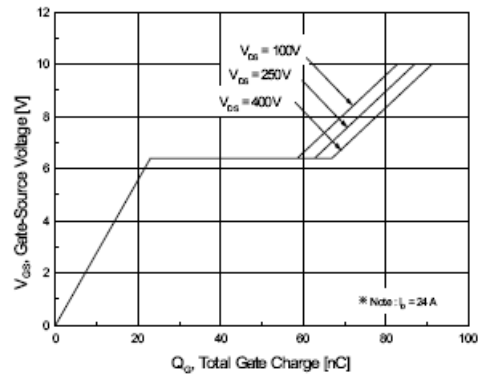


Fig.6 Gate Charge Characteristics

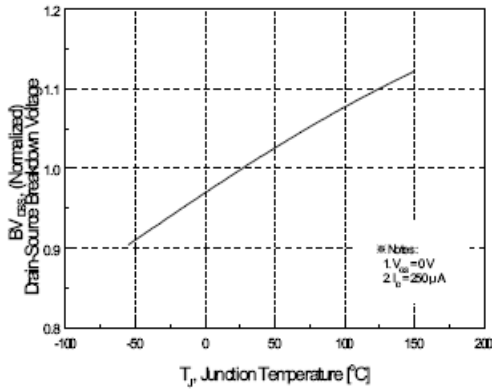


Fig.7 Breakdown Voltage Variation

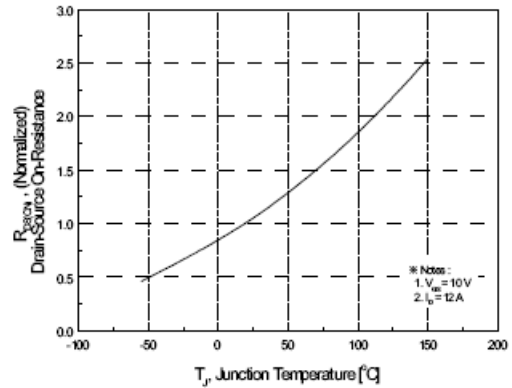


Fig.8 On-Resistance Variation vs. Temperature

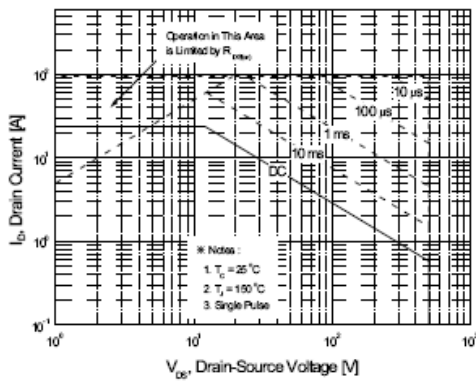


Fig.9 Maximum Safe Operation Area

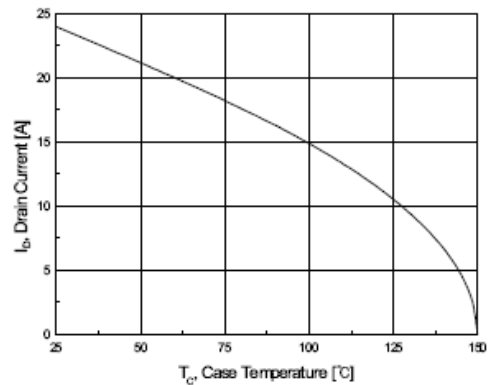


Fig.10 Maximum Drain Current vs Case Temperature

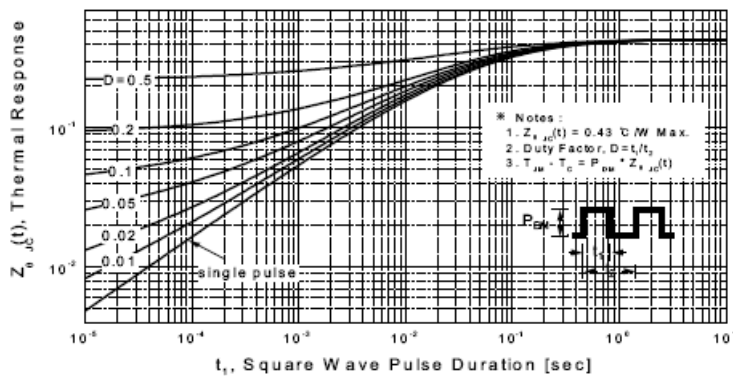


Fig.11 Transient Thermal Response Curve

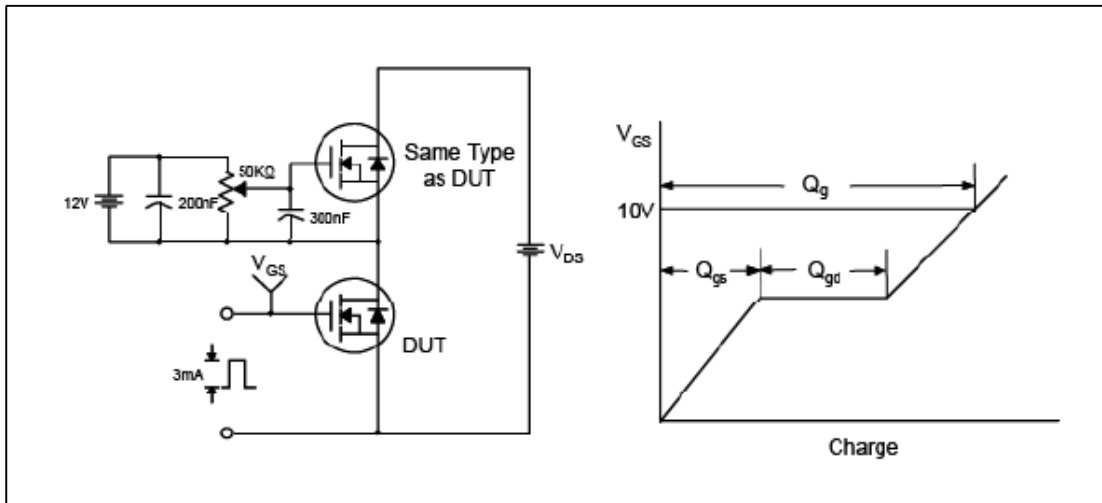


Fig.12 Gate Test Circuit & Waveform

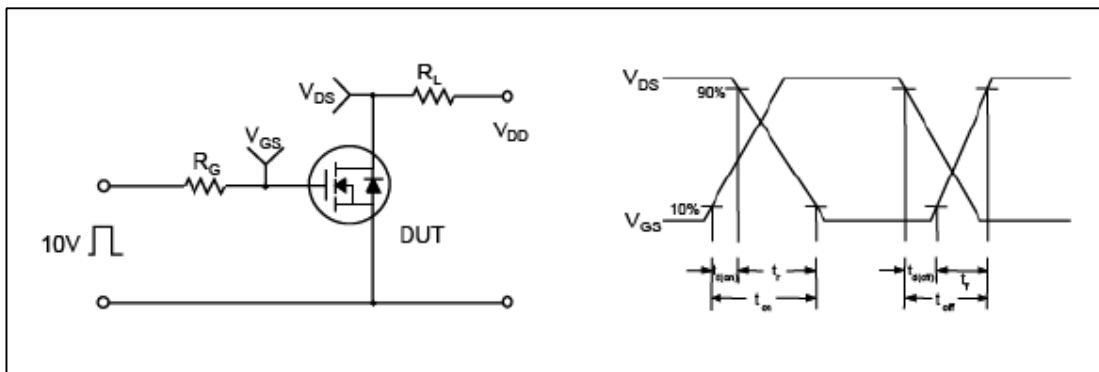


Fig.13 Resistive Switching Test Circuit & Waveform

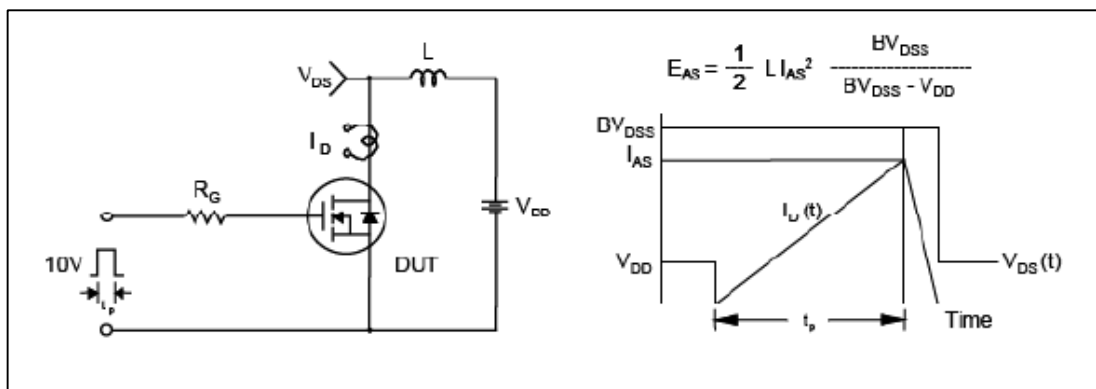


Fig.14 Unclamped Inductive Switching Test Circuit &

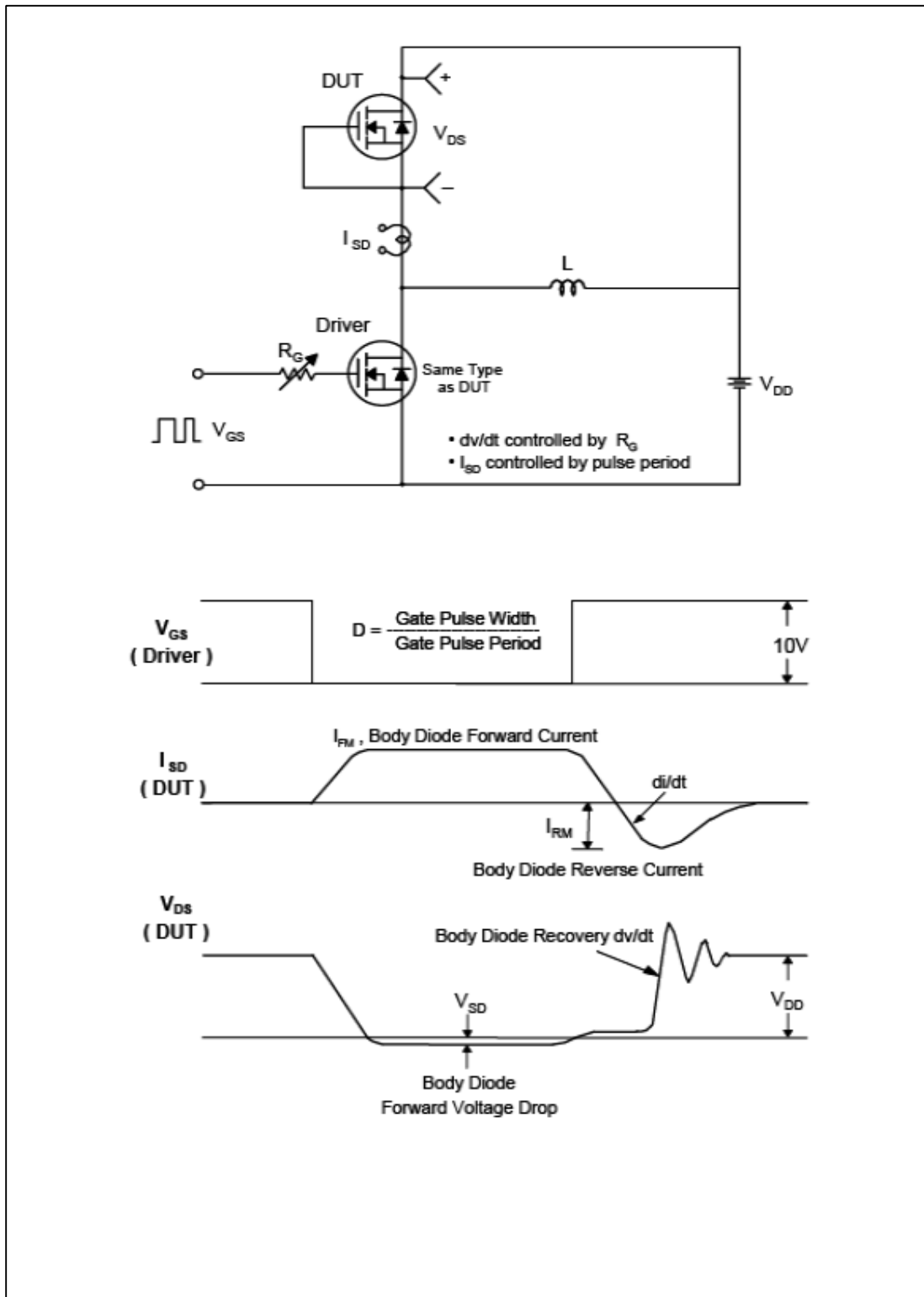


Fig.15 Peak Diode Recovery dv/dt Test Circuit & Waveform

TO-247 Package Dimension

